



Material Content Data Sheet



Sales Product Name		BSZ042N04NS G		Issued		20. July 2018		
MA#		MA000469802						
Package		PG-TSDSON-8-2		Weight*		40.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.836	4.57	4.57	45676	45676
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52	
	non noble metal	zinc	7440-66-6	0.008	0.02		209	
	non noble metal	iron	7439-89-6	0.168	0.42		4170	
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169328	173759
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	884	884
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909
plastics	plastics	epoxy resin	-	1.882	4.68		46819	
	inorganic material	silicondioxide	60676-86-0	16.356	40.70	45.47	406823	454551
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9630	9630
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23942	23942
solder	non noble metal	tin	7440-31-5	0.037	0.09		916	
	noble metal	silver	7440-22-4	0.046	0.11		1145	
	non noble metal	lead	7439-92-1	1.759	4.37	4.57	43743	45804
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.086	0.21		2145	
	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87085	89364
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47	
	non noble metal	zinc	7440-66-6	0.008	0.02		188	
	non noble metal	iron	7439-89-6	0.151	0.38		3753	
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152402	156390
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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